

Product/process change notification

PCN N° 2023-059-A

Dear customer,

Please find attached our Infineon Technologies AG PCN:

Phase out of Kyocera KEG300 mold compound for several assembly locations and change of lead finish from tin dip to electro plating at Tijuana, Mexico for dedicated TO220-3 & TO247-3 products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **2024-01-19**
- Infineon aligns with the widely recognized JEDEC STANDARD “**JESD46**“, which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG

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Chairman of the Supervisory Board Dr. Herbert Diess

Management Board Jochen Hanebeck (CEO), Elke Reichart, Dr. Sven Schneider, Andreas Urschitz, Dr. Rutger Wijburg

Registered office Neubiberg Commercial register Amtsgericht München HRB 126492

Product/process change notification

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► **Products affected**

Please refer to attached affected product list
 “pcn_2023-059-A_[customer-no].pdf”
 Please refer to 3_cip23059_a for the list of products affected by
 the lead finish change

► **Detailed change information**

Subject Phase out of Kyocera KEG300 mold compound for several
 assembly locations and change of lead finish from tin dip to electro
 plating at Tijuana, Mexico for dedicated TO220-3 & TO247-3
 products

Reason To ensure continuity of mold compound supply due to Kyocera
 KEG300 end of life and to further ensure our product performance
 with lead-free electroplating finish

| Description | Old | New |
|--|------------------|--------------------------------------|
| Assembly materials: Mold compound | ■ Kyocera KEG300 | ■ Sumitomo EME-E500 |
| Assembly materials: Lead finish (Tijuana only) | ■ Tin dip finish | ■ Lead-free electroplating finish |

► **Product identification**

Internal traceability is assured via Baunumber and datecode

► **Impact of change**

No impact on electrical performance. Quality and reliability verified
 by qualification. There is no change in form, fit and function

► **Attachments**

| | |
|------------------------------------|-----------------------|
| “pcn_2023-059-A_[customer-no].pdf” | affected product list |
| 2_cip23059_a | qualification report |
| 3_cip23059_a | information package |

► **Time schedule**

- Final qualification report available
- First samples available on request
- Intended start of delivery 2024-02-29 or earlier based on customer approval

If you have any questions, please do not hesitate to contact your local sales office.